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2013年9月

# FGH15T120SMD

# 1200 V, 15 A 场截止沟道 IGBT

#### 特性

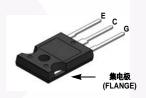
- FS 沟道技术,正温度系数
- 高速开关
- 低饱和电压: V<sub>CE(sat)</sub> =1.8 V @ I<sub>C</sub>=15 A
- I<sub>LM</sub>(1) 部件 100% 检测
- 高输入阻抗
- 符合 RoHS 标准

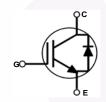
#### 应用

• 光伏逆变器、焊机、 UPS 和 PFC 应用

### 概述

通过采用创新的场截止沟道 IGBT 技术,飞兆半导体新型系列的 场截止沟道 IGBT 可为光伏逆变器、 UPS、焊机和 PFC 等硬开 关应用提供最佳性能。





## 绝对最大额定值 Tc=25℃ 除非另有说明

符号	说明		额定值	单位
V <sub>CES</sub>	集电极 - 发射极之间电压		1200	V
V <sub>GES</sub>	栅极一发射极间电压		±25	V
*GES	瞬态栅极一发射极间电压		±30	V
I <sub>C</sub>	集电极电流	@ T <sub>C</sub> =25°C	30	A
	集电极电流	@ T <sub>C</sub> =100°C	15	Α
I <sub>LM</sub> (1)	箝位感性负载电流	@ T <sub>C</sub> =25°C	60	Α
I <sub>CM</sub> (2)	集电极脉冲电流		60	А
l <sub>F</sub>	二极管正向连续电流	@ T <sub>C</sub> =25°C	30	Α
	二极管正向连续电流	@ T <sub>C</sub> =100°C	15	Α
I <sub>FM</sub>	二极管最大正向电流		100	A
P <sub>D</sub>	最大功耗	@ T <sub>C</sub> =25°C	333	W
. р	最大功耗	@ T <sub>C</sub> =100°C	167	W
T <sub>J</sub>	工作结温		-55 至 +175	°C
T <sub>stg</sub>	存储温度范围		-55 至 +175	°C
T <sub>L</sub>	用于焊接的最大引脚温度,距离外壳 1/8",持续 5 秒		300	°C

#### 热性能

符号	参数	典型值	最大值	单位
$R_{\theta JC}(IGBT)$	结点 - 壳体的热阻		0.45	°C/W
R <sub>θJC</sub> (二极管)	结点 - 壳体的热阻		2.0	°C/W
$R_{\theta JA}$	结至环境热阻		40	°C/W

**注意:** 1. Vcc=600 V, V<sub>GE</sub>=15 V, I<sub>C</sub>=60 A, R<sub>G</sub>=34 Ω, 感性负载

2. 受限于 Tjmax

<u>封装标识与定购信息</u>

器件标识	器件	封装	卷尺寸	带宽	数量
FGH15T120SMD	FGH15T120SMD_F155	TO-247G03	-	-	30

# IGBT 的电气特性 Tc=25℃ 除非另有说明

符号	参数	测试条件	最小值	典型值	最大值	单位
关断特性						
BV <sub>CES</sub>	集电极 - 发射极击穿电压	V <sub>GE</sub> =0 V, I <sub>C</sub> =250 μA	1200	-	-	V
I <sub>CES</sub>	集电极切断电流	V <sub>CE</sub> =V <sub>CES</sub> , V <sub>GE</sub> =0 V	-	-	250	μΑ
I <sub>GES</sub>	G-E 漏电流	V <sub>GE</sub> =V <sub>GES</sub> , V <sub>CE</sub> =0 V	-	-	±400	nA
导通特性						
V <sub>GE(th)</sub>	G-E 阈值电压	$I_C$ =15 mA, $V_{CE}$ = $V_{GE}$	4.9	6.2	7.5	V
		I <sub>C</sub> =15 A, V <sub>GE</sub> =15 V T <sub>C</sub> =25°C	-	1.8	2.4	V
V <sub>CE(sat)</sub>	集电极 - 发射极间饱和电压	I <sub>C</sub> =15 A, V <sub>GE</sub> =15 V, T <sub>C</sub> =175°C	-	1.9	-	V
动态特性						
C <sub>ies</sub>	输入电容		-	1460	-	pF
C <sub>oes</sub>	输出电容	V <sub>CE</sub> =30 V <sub>,</sub> V <sub>GE</sub> =0 V, f=1 MHz	-	65	-	pF
C <sub>res</sub>	反向传输电容	1-1 1011 12	-	37	-	pF
开关特性			·			
t <sub>d(on)</sub>	导通延迟时间		-	32	-	ns
t <sub>r</sub>	上升时间		-	47	-	ns
t <sub>d(off)</sub>	关断延迟时间	$V_{CC}$ =600 V, $I_{C}$ =15 A, $R_{G}$ =34 $\Omega$ , $V_{GE}$ = 15 V,感性负载, $T_{C}$ =25°C	-	490	-	ns
t <sub>f</sub>	下降时间		-	12	-	ns
E <sub>on</sub>	导通开关损耗	————	-	1.15	-	mJ
E <sub>off</sub>	关断开关损耗		-	0.46	-	mJ
E <sub>ts</sub>	总开关损耗		-	1.61	-	mJ
t <sub>d(on)</sub>	导通延迟时间		- /	32	-	ns
t <sub>r</sub>	上升时间		-	42	-	ns
t <sub>d(off)</sub>	关断延迟时间	V <sub>CC</sub> =600 V, I <sub>C</sub> =15 A,	-	510	-	ns
t <sub>f</sub>	下降时间	$R_G=34 \Omega$ , $V_{GE}=15 V$ ,	-	24	- /	ns
E <sub>on</sub>	导通开关损耗	感性负载, T <sub>C</sub> =175°C	-	1.86	-	mJ
E <sub>off</sub>	关断开关损耗		-	0.70	-	mJ
E <sub>ts</sub>	总开关损耗		-	2.56	-	mJ
Qg	总栅极电荷		-	128	-	nC
Q <sub>ge</sub>	栅极一发射极间电荷	V <sub>CE</sub> =600 V, I <sub>C</sub> =15 A, V <sub>GE</sub> =15 V	-	11	-	nC
Q <sub>gc</sub>	栅极一发射极间电荷	V GE-10 V	-	70	-	nC

# 二极管电气特性 Tc=25°C 除非另有说明

符号	参数	测试条件	最小值	典型值	最大值	单位
V <sub>FM</sub>	м 二极管正向电压	I <sub>F</sub> =15 A, T <sub>C</sub> =25°C	-	2.8	3.7	V
1 101		I <sub>F</sub> =15 A, T <sub>C</sub> =175°C	-	2.3	-	V
t <sub>rr</sub>	二极管反向恢复时间	V <sub>R</sub> =600 V, I <sub>F</sub> =15 A,	-	72	-	ns
I <sub>rr</sub>	二极管反向恢复峰值电流	$di_F/dt=200 A/\mu s$ , $T_C = 25$ °C	-	7.4	-	Α
Q <sub>rr</sub>	二极管反向恢复电荷		-	270	-	nC
E <sub>rec</sub>	反向恢复电能	$V_R = 600 \text{ V}, I_F = 15 \text{ A},$	-	120	-	μJ
t <sub>rr</sub>	二极管反向恢复时间	$di_F/dt=200 A/\mu s$ , $T_C = 175$ °C	-	183	-	ns
Irr	二极管反向恢复峰值电流		-	12	-	Α
Q <sub>rr</sub>	二极管反向恢复电荷		-	1085	-	nC

#### 图 1. 典型输出特性

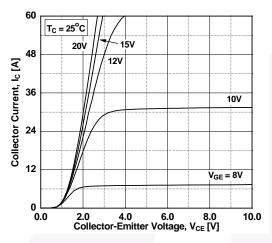


图 2. 典型输出特性

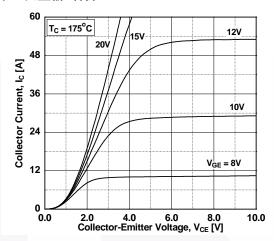


图 3. 典型饱和电压特性

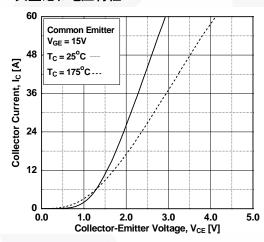


图 4. 饱和电压与壳温的关系 (在可变电流强度下)

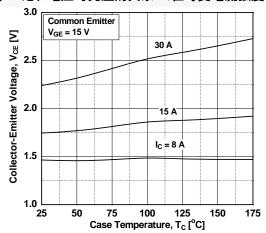


图 5. 饱和电压与 V<sub>GE</sub> 的关系

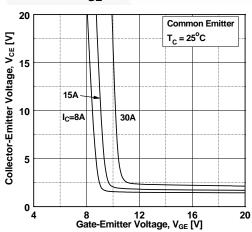


图 6. 饱和电压与 VGE 的关系

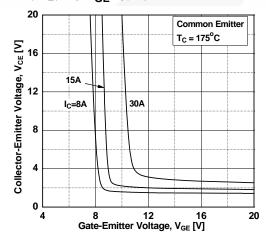


图 7. 电容特性

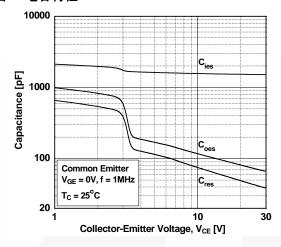


图 8. 栅极电荷特性

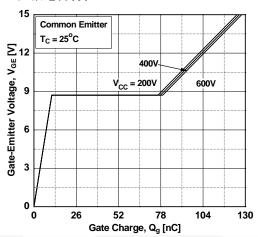


图 9. 导通特性与栅极电阻的关系

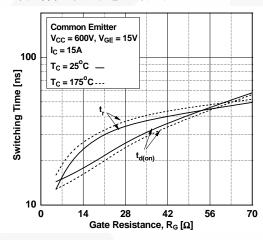


图 10. 关断特性与栅极电阻的关系

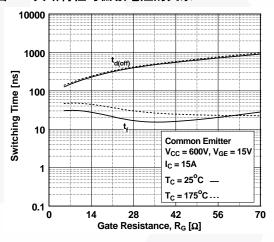


图 11. 开关损耗与栅极电阻的关系

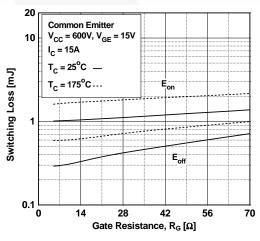
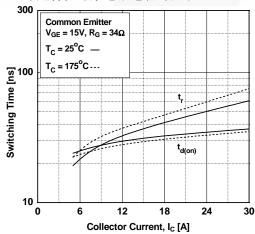
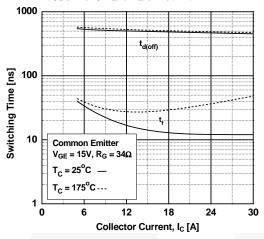


图 12. 导通特性与集电极电流的关系



#### 图 13. 关断特性与集电极电流的关系



#### 图 14. 开关损耗与集电极电流的关系

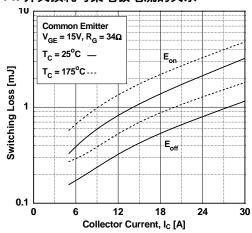


图 15. 负载电流与频率的关系

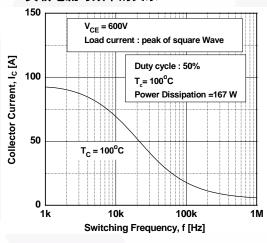


图 16. SOA 特性

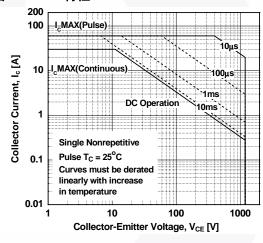


图 17. 正向特性

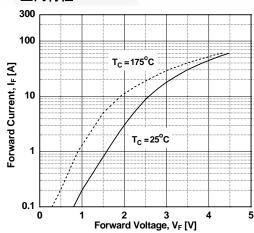


图 18. 反向恢复电流

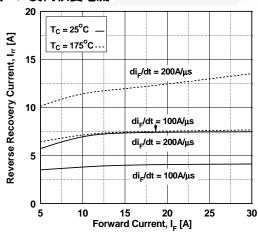


图 19. 反向恢复时间

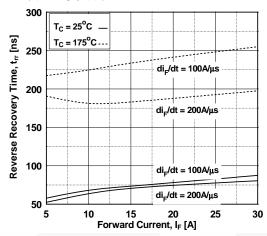


图 20. 存储电荷

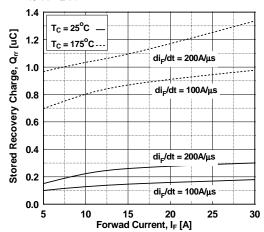


图 21. IGBT 瞬态热阻抗

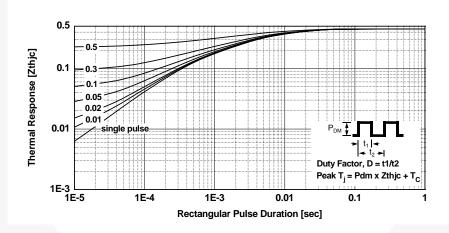
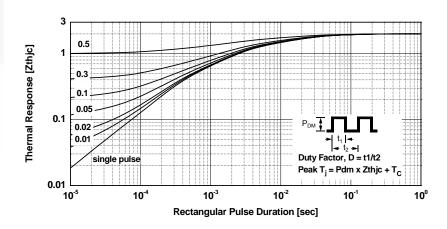
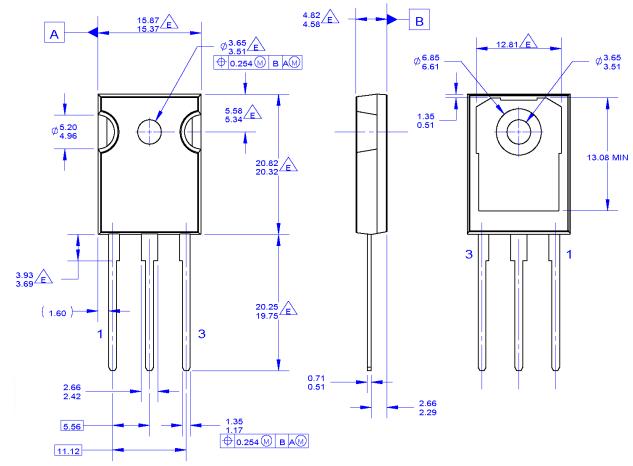


图 22. 二极管瞬态热阻抗



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#### 图 23. TO-247, 模塑, 3 引脚, JEDEC 变体 AB (有效)

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